

# SP10-RJ4530M

## SFP+ 10Gb/s Copper-T 30m RJ45

### PRODUCT FEATURES

- Support 10Gbase-T/5Gbase-T/2.5Gbase-T/1000base-T
- Hot-pluggable SFP footprint
- Compact RJ-45 connector assembly
- Single +3.3V power supply
- 10 Gigabit Ethernet over Cat 6a cable
- Operating temperature: 0°C to +70°C
- RoHS compliant and lead-free



### APPLICATIONS

- 10GBASE-T 10G Ethernet

### PRODUCT DESCRIPTION

Photonics Valley's SP10-RJ4530M SFP+ Copper-T 10Gbps transceiver is based on the SFP Multi Source Agreement (MSA). They are compatible with the 10Gbase-T / 5Gbase-T / 2.5Gbase-T / 1000base-T standards as specified in IEEE Std 802.3. SFP+-10GBASE-T uses the SFP's RX LOS (must be pulled up on host) pin for link indication. If pull up or open SFP's TX\_DISABLE pin, PHY IC be reset.

### General Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Data Rate	BR	1		10	Gbps
I <sup>2</sup> C Clock Rate		0		200,000	Hz

Notes: Clock tolerance is +/- 50 ppm

## Environmental Specifications

Automatic crossover detection is enabled. External crossover cable is not required

Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Operating Temperature	Top	0		70	°C	Case temperature
Storage Temperature	Tsto	-40		85	°C	Ambient temperature

## Cable Length

Standard	Cable	Reach	Host Port
10Gbase-T	CAT6A	30m	XFI
5Gbase-T/2.5Gbase-t	CAT5E	50m	5GBase-R/2.5GBase-X
1000base-T	CAT5E	100m	1000base-FX

## SFP to Host Connector Pin Out

Pin	Symbol	Name/Description	Ref.
1	VEET	Transmitter Ground (Common with Receiver Ground)	1
2	TFAULT	Transmitter Fault. Not supported.	
3	TDIS	Transmitter Disable. Laser output disabled on high or open.	2
4	MOD_DEF(2)	Module Definition 2. Data line for Serial ID.	3
5	MOD_DEF(1)	Module Definition 1. Clock line for Serial ID.	3
6	MOD_DEF(0)	Module Definition 0. Grounded within the module.	3
7	Rate Select	No connection required	
8	LOS	High indicates no linked. low indicates linked.	4
9	VEER	Receiver Ground (Common with Transmitter Ground)	1
10	VEER	Receiver Ground (Common with Transmitter Ground)	1
11	VEER	Receiver Ground (Common with Transmitter Ground)	1
12	RD-	Receiver Inverted DATA out. AC Coupled	
13	RD+	Receiver Non-inverted DATA out. AC Coupled	
14	VEER	Receiver Ground (Common with Transmitter Ground)	1
15	VCCR	Receiver Power Supply	
16	VCCT	Transmitter Power Supply	
17	VEET	Transmitter Ground (Common with Receiver Ground)	1
18	TD+	Transmitter Non-Inverted DATA in. AC Coupled.	
19	TD-	Transmitter Inverted DATA in. AC Coupled.	
20	VEET	Transmitter Ground (Common with Receiver Ground)	1

Notes:

1. Circuit ground is connected to chassis ground
2. PHY disabled on  $T_{DIS} > 2.0V$  or open, enabled on  $T_{DIS} < 0.8V$
3. Should be pulled up with 4.7k - 10k Ohms on host board to a voltage between 2.0 V and 3.6 V. MOD\_DEF(0) pulls line low to indicate module is plugged in.
4. LVTTTL compatible with a maximum voltage of 2.5V.

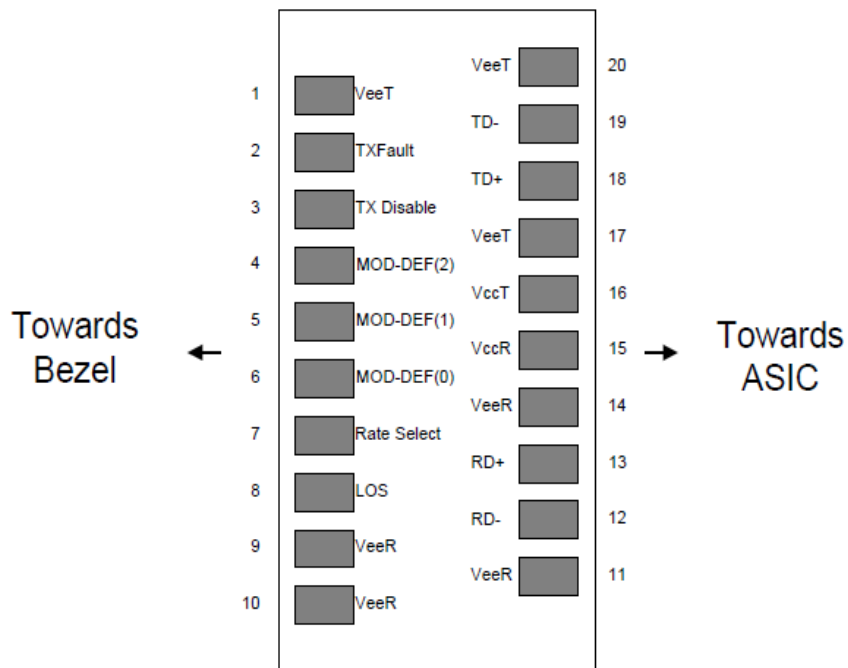


Figure 1. Diagram of host board connector block pin numbers and names

### 3.3V Volt Electrical Power Interface

The SFP+-10GBASE-T has an input voltage range of 3.3 V +/- 5%. The 4V maximum voltage is not allowed for continuous operation.

3.3 Volt Electrical Power Interface						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Supply Current	I <sub>s</sub>		700	900	mA	3.0W max power over full range of voltage and temperature. See caution note below
Input Voltage	V <sub>cc</sub>	3.13	3.3	3.47	V	Referenced to GND

Maximum Voltage	Vmax			4	V	
Surge Current	I <sub>surge</sub>		TBD		mA	Hot plug above steady state current. See caution note below

Notes: Power consumption and surge current are higher than the specified values in the SFP MSA

## Low-Speed Signals

MOD\_DEF(1) (SCL) and MOD\_DEF(2) (SDA), are open drain CMOS signals (see section VII, "Serial Communication Protocol"). Both MOD\_DEF(1) and MOD\_DEF(2) must be pulled up to host Vcc

Low-Speed Signals, Electronic Characteristics						
Parameter	Symbol	Min	Max	unit	Notes/Conditions	
SFP Output LOW	VOL	0	0.5	V	4.7k to 10k pull-up to host_Vcc, measured at host side of connector	
SFP Output HIGH	VOH	host_Vcc -0.5	host_Vcc + 0.3	V	4.7k to 10k pull-up to host_Vcc, measured at host side of connector	
SFP Input LOW	VIL	0	0.8	V	4.7k to 10k pull-up to Vcc, measured at SFP side of connector	
SFP Input HIGH	VIH	2	Vcc + 0.3	V	4.7k to 10k pull-up to Vcc, measured at SFP side of connector	

## High-Speed Electrical Interface

All high-speed signals are AC-coupled internally.

High-Speed Electrical Interface, Transmission Line-SFP						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Line Frequency	f <sub>L</sub>		125		MHz	5-level encoding, per IEEE 802.3
Tx Output Impedance	Z <sub>out,TX</sub>		100		Ohm	Differential, for all frequencies between 1MHz and 125MHz
Rx Input Impedance	Z <sub>in,RX</sub>		100		Ohm	Differential, for all frequencies between 1MHz and 125MHz

High-Speed Electrical Interface, Host-SFP						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Single ended data input swing	V <sub>insing</sub>	250		1200	mV	Single ended
Single ended data output swing	V <sub>outsing</sub>	350		800	mV	Single ended

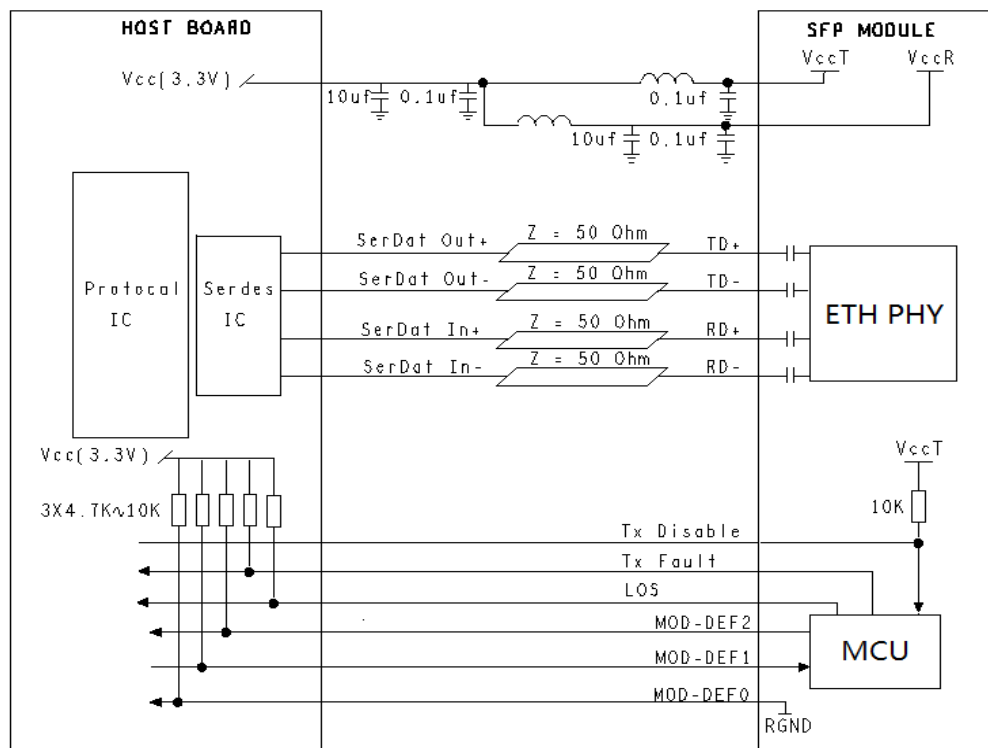
Rise/Fall Time	$T_r, T_f$	175	psec	20%-80%
Tx Input Impedance	$Z_{in}$	50	Ohm	Single ended
Rx Output Impedance	$Z_{out}$	50	Ohm	Single ended

## General Specifications

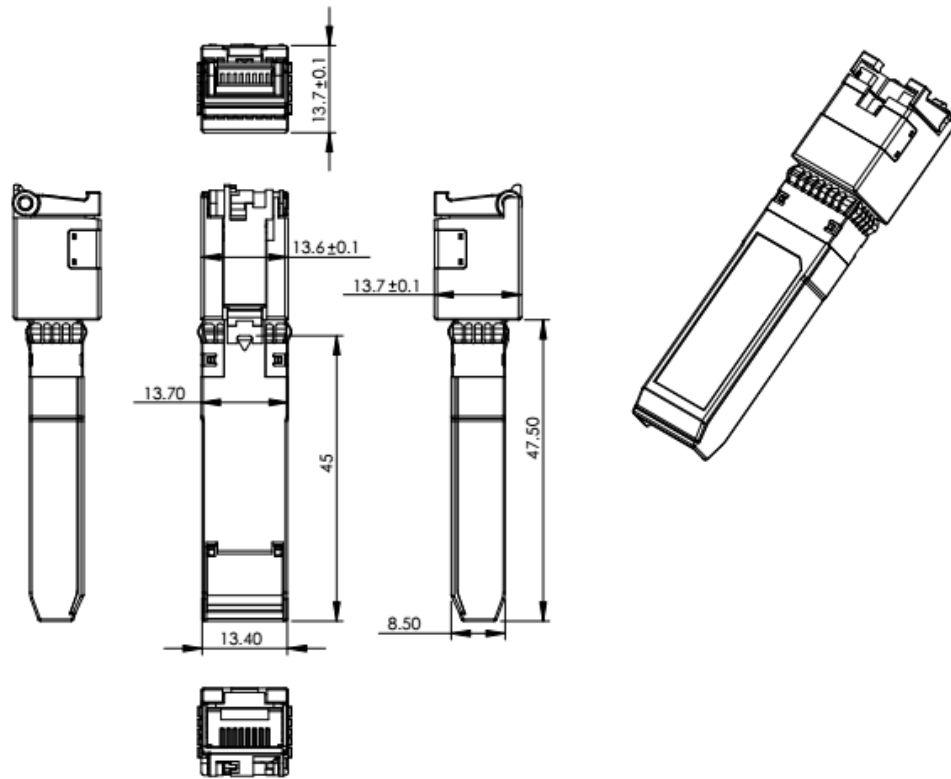
General						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Data Rate	BR	1		10	Gb/sec	IEEE 802.3 compatible. See Notes 1,2 below

**Notes:** Clock tolerance is +/- 50 ppm

## Recommended Application Circuit



## Mechanical Specifications (Unit: mm)



## Regulatory Compliance

Feature	Reference	Performance
Electrostatic discharge (ESD)	IEC/EN 61000-4-2	Compatible with standards
Electromagnetic Interference (EMI)	FCC Part 15 Class B EN 55022 Class B (CISPR 22A)	Compatible with standards
Laser Eye Safety	IEC/EN 60825-1, 2	Class 1 laser product
ROHS	2002/95/EC	Compatible with standards
EMC	EN61000-3	Compatible with standards